

# SN74AC240-Q1 Automotive Octal Buffer/Driver with 3-State Outputs

## 1 Features

- Qualified for automotive applications
- Operation of 2V to 6V  $V_{CC}$
- Inputs accept voltages to 6V
- Max  $t_{pd}$  of 6.5ns at 5V

## 2 Applications

- [Debounce a switch](#)
- [Redrive digital signals](#)
- [Drive transmission lines with logic](#)

## 3 Description

This octal buffer and line driver is designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

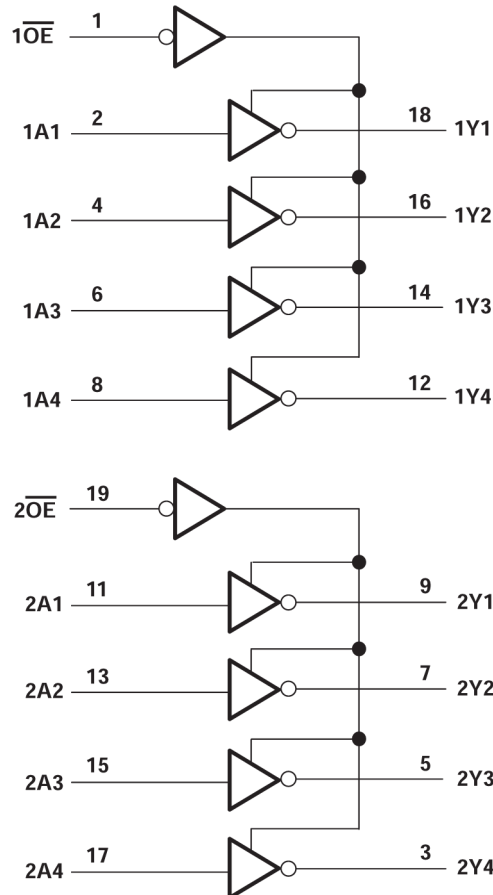
### Package Information

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>	BODY SIZE <sup>(3)</sup>
SN74AC240-Q1	PW (TSSOP, 20)	6.5mm × 6.4mm	6.5mm × 4.4mm

(1) For more information, see [Section 11](#).

(2) The package size (length × width) is a nominal value and includes pins, where applicable.

(3) The body size (length × width) is a nominal value and does not include pins.



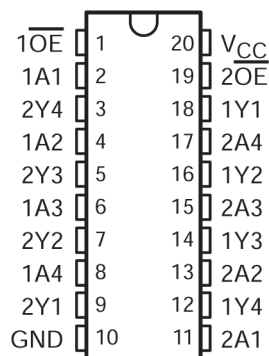
Logic Diagram (Positive Logic)



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## 4 Pin Configuration and Functions



**Figure 4-1. DW or PW Package (Top View)**

**Table 4-1. Pin Functions**

NAME <sup>(1)</sup>	PIN	TYPE	DESCRIPTION
1OE	1	I	Output enable 1
1A1	2	I	1A1 input
2Y4	3	O	2Y4 output
1A2	4	I	1A2 input
2Y3	5	O	2Y3 output
1A3	6	I	1A3 input
2Y2	7	O	2Y2 output
1A4	8	I	1A4 input
2Y1	9	O	2Y1 output
GND	10	—	Ground pin
2A1	11	I	2A1 input
1Y4	12	O	1Y4 output
2A2	13	I	2A2 input
1Y3	14	O	1Y3 output
2A3	15	I	2A3 input
1Y2	16	O	1Y2 output
2A4	17	I	2A4 input
1Y1	18	O	1Y1 output
2OE	19	I	Output enable 2
VCC	20	—	Power pin

(1) Signal Types: I = Input, O = Output, I/O = Input or Output

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	-0.5	7	V
V <sub>I</sub> <sup>(2)</sup>	Input voltage range	-0.5	V <sub>CC</sub> + 0.5	V
V <sub>O</sub> <sup>(2)</sup>	Output voltage range	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	(V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> )		±20 mA
I <sub>OK</sub>	Output clamp current	(V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )		±20 mA
I <sub>O</sub>	Continuous output current	(V <sub>O</sub> = 0 to V <sub>CC</sub> )		±50 mA
T <sub>stg</sub>	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 5.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	2	6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 3 V	2.1	V
		V <sub>CC</sub> = 4.5 V	3.15	
		V <sub>CC</sub> = 5.5 V	3.85	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 3 V	0.9	V
		V <sub>CC</sub> = 4.5 V	1.35	
		V <sub>CC</sub> = 5.5 V	1.65	
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 3 V	-12	mA
		V <sub>CC</sub> = 4.5 V	-24	
		V <sub>CC</sub> = 5.5 V	-24	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 3 V	12	mA
		V <sub>CC</sub> = 4.5 V	24	
		V <sub>CC</sub> = 5.5 V	24	
Δt/Δv	Input transition rise or fall rate		8	ns/V
T <sub>A</sub>	Operating free-air temperature	-40	125	°C

- (1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### 5.3 Thermal Information

THERMAL METRIC <sup>(1)</sup>		DW	PW	UNIT
		20 PINS	20 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance <sup>(2)</sup>	58	126.2	°C/W

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).
- (2) The package thermal impedance is calculated in accordance with JESD 51-7.

## 5.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = –40°C TO 125°C		T <sub>A</sub> = –40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = –50 µA		3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
	I <sub>OH</sub> = –12 mA		3 V	2.56			2.4		2.46		
			4.5 V	3.86			3.7		3.76		
	I <sub>OH</sub> = –24 mA		5.5 V	4.86			4.7		4.76		
			5.5 V				3.85				
V <sub>OL</sub>	I <sub>OL</sub> = 50 µA		3 V			0.1		0.1		0.1	V
			4.5 V			0.1		0.1		0.1	
			5.5 V			0.1		0.1		0.1	
	I <sub>OL</sub> = 12 mA		3 V			0.36		0.5		0.44	
			4.5 V			0.36		0.5		0.44	
	I <sub>OL</sub> = 24 mA		5.5 V			0.36		0.5		0.44	
			5.5 V				1.65				
I <sub>I</sub>	Data inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V			±0.1		±1		±1	µA
	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND				±0.1		±1		±1	
I <sub>OZ</sub> <sup>(2)</sup>	V = V <sub>CC</sub> or GND, V(OE) = V <sub>IL</sub> or V <sub>IH</sub>		5.5 V			±0.25		±5		±2.5	µA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0		5.5 V			4		80		40	µA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND		5 V		2.5						pF

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

(2) For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

## 5.5 Switching Characteristics, V<sub>CC</sub> = 3.3 V ± 0.3 V

over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V ± 0.3 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T <sub>A</sub> = 25°C			T <sub>A</sub> = –40°C TO 125°C		T <sub>A</sub> = –40°C TO 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	Y	1.5	6	8	1	11	1	9	ns
t <sub>PHL</sub>			1.5	5.5	8	1	10.5	1	8.5	
t <sub>PZH</sub>	OE	Y	1.5	6	10.5	1	11.5	1	11	ns
t <sub>PZL</sub>			1.5	7	10	1	13	1	11	
t <sub>PHZ</sub>	OE	Y	1.5	7	10	1	12.5	1	10.5	ns
t <sub>PLZ</sub>			1.5	7.5	10.5	1	13.5	1	11.5	

## 5.6 Switching Characteristics, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$

over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

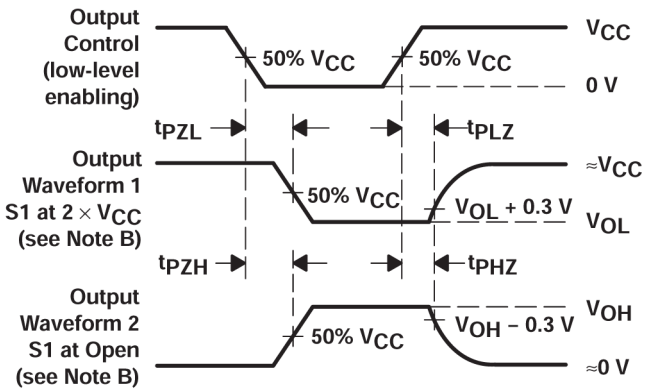
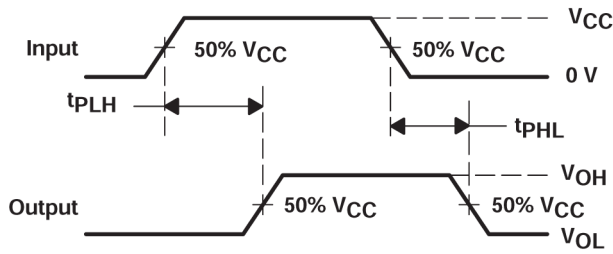
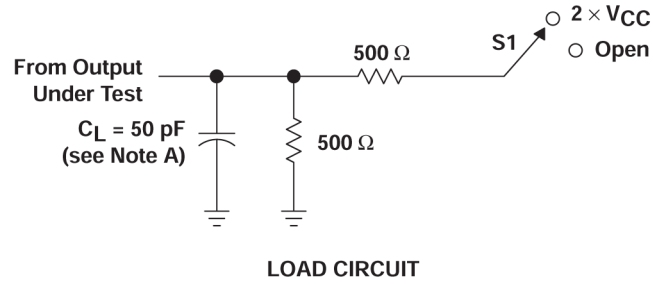
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C TO } 125^\circ\text{C}$		$T_A = -40^\circ\text{C TO } 85^\circ\text{C}$		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A	Y	1.5	4.5	6.5	1	8.5	1	7	ns
$t_{PHL}$			1.5	4.5	6	1	8	1	6.5	
$t_{PZH}$	$\overline{OE}$	Y	1.5	5	7	1	9	1	8	ns
$t_{PZL}$			1.5	5.5	8	1	10.5	1	8.5	
$t_{PHZ}$	$\overline{OE}$	Y	2.5	6.5	9	1	10.5	1	9.5	ns
$t_{PLZ}$			2	6.5	9	1	11	1	9.5	

## 5.7 Operating Characteristics

$V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
$C_{pd}$	Power dissipation capacitance per buffer/driver	$C_L = 50\text{ pF}$ , $f = 1\text{ MHz}$	45	pF

## 6 Parameter Measurement Information



- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
- D. The outputs are measured one at a time, with one input transition per measurement.

**Figure 6-1. Load Circuit and Voltage Waveforms**

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	Open

## 7 Detailed Description

### 7.1 Overview

The SN74AC240 device is organized as two 4-bit buffers/drivers with separate output-enable ( $\overline{OE}$ ) inputs. When  $\overline{OE}$  is low, the device passes inverted data from the A inputs to the Y outputs. When  $\overline{OE}$  is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

### 7.2 Functional Block Diagram

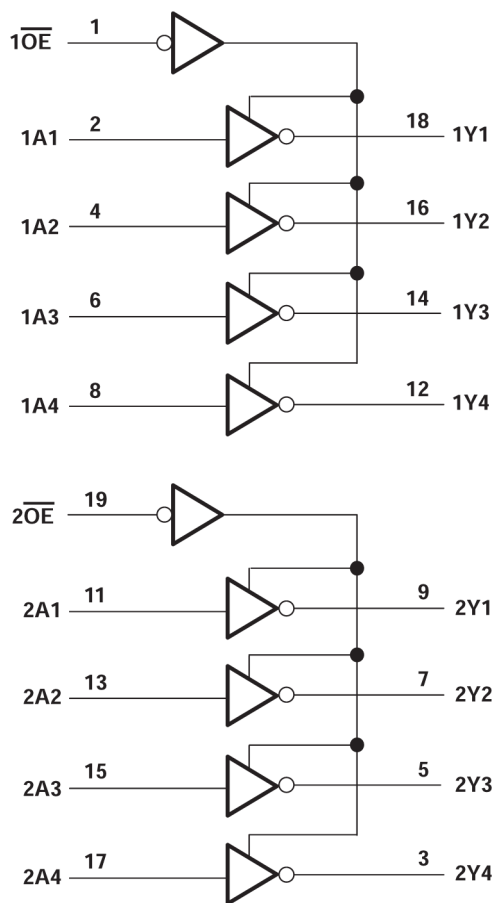


Figure 7-1. Logic Diagram (Positive Logic)

### 7.3 Device Functional Modes

Table 7-1. Function Table (Each Buffer)

INPUTS		OUTPUT Y
$\overline{OE}$	A	
L	H	L
L	L	H
H	X	Z



## 8 Application and Implementation

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### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

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### 8.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- $\mu$ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. The 0.1- $\mu$ F and 1- $\mu$ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results, as shown in the following layout example.

### 8.2 Layout

#### 8.2.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices, inputs must never be left floating. In many cases, functions or parts of functions of digital logic devices are unused (for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used). Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or  $V_{CC}$ , whichever makes more sense for the logic function or is more convenient.

## 8.2.2 Layout Example

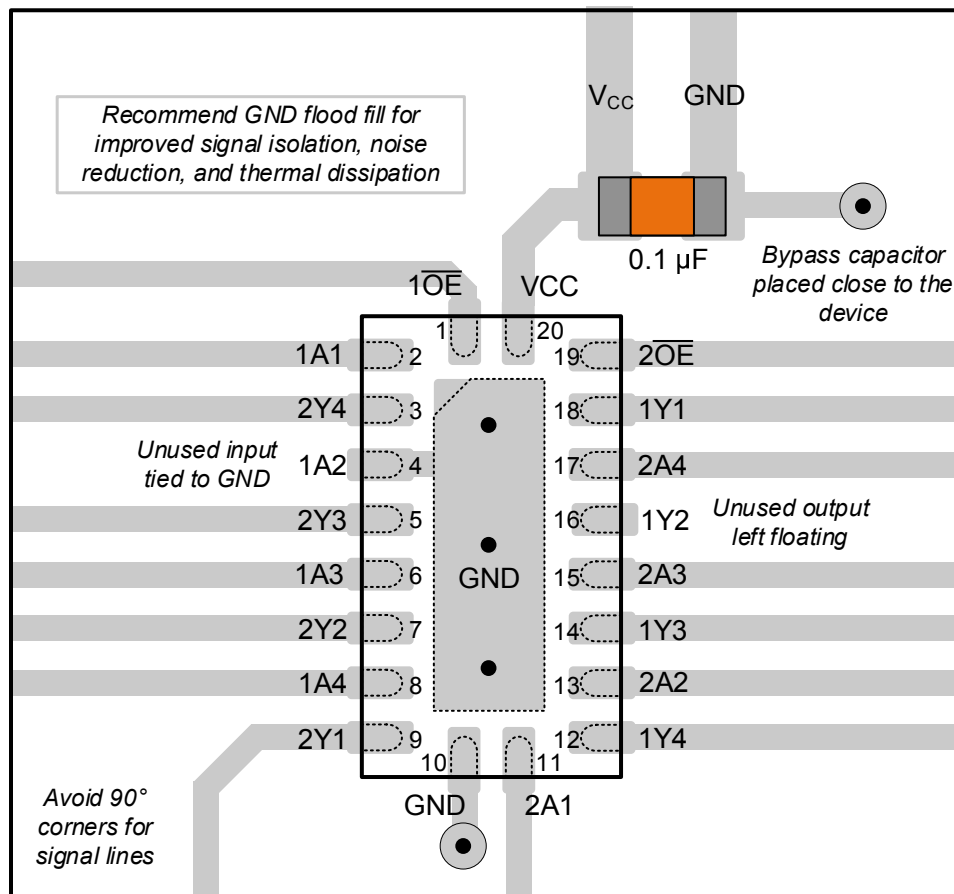


Figure 8-1. Example Layout for the SN74AC240-Q1

## 9 Device and Documentation Support

### 9.1 Documentation Support (Analog)

#### 9.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**Table 9-1. Related Links**

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74AC240-Q1	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>

### 9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 9.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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### 9.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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### 9.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 9.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (January 2008) to Revision B (March 2024)	Page
• Added <i>Applications</i> section, <i>Package Information</i> table, <i>Pin Functions</i> table, <i>Thermal Information</i> table, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	1
• Updated RθJA value: PW = 83 to 126.2, all values in °C/W .....	4

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SN74AC240QPWRQ1</a>	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AC240Q
SN74AC240QPWRQ1.A	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AC240Q

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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### OTHER QUALIFIED VERSIONS OF SN74AC240-Q1 :

- Catalog : [SN74AC240](#)

- Military : [SN54AC240](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC240QPWRQ1	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC240QPWRQ1	TSSOP	PW	20	2000	353.0	353.0	32.0



## TSSOP - 1.2 mm max height

## SMALL OUTLINE PACKAGE



1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



# EXAMPLE BOARD LAYOUT

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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